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Memory Specifications

Graphics Specifications

Expansion Options

I/O Specifications

Package Specifications

Advanced Technologies

Intel® Data Protection Technology

Intel® Platform Protection Technology

COMPATIBLE PRODUCTS

PRODUCT IMAGES

ORDERING / SSPECS / STEPPINGS

Status	Launched
Launch Date	Q1'12
Limited 3-year Warranty	Yes
Extended Warranty Available for Purchase (Select Countries)	Yes
# of QPI Links	2
Board Form Factor	SSI EEB 12" x 13"
Chassis Form Factor	Pedestal
Socket	Socket R
Integrated Systems Available	No
Integrated BMC with IPMI	IPMI 2.0
Rack-Friendly Board	Yes
Embedded Options Available	Yes
Max TDP	135 W
Included Items	Intel® Server Board S2600CO4 and attention document. Below items are not included in 10 pack sku, but included In Disti 5 Pack only: I/O shield, cables, configuration labels, Intel® Server Deployment & Management DVD, Quick Start User's Guide.
Recommended Customer Price	N/A
Description	Intel® Server Board S2600CO4, Premium server board supporting two E5-2600 CPUs up to 130W, 16 DIMMs with four 1Gb Ethernet ports
Target Market	Embedded
Additional Information URL	Link

Memory Specifications	
Max Memory Size (dependent on memory type)	512 GB
Memory Types	DDR3 ECC UDIMM/LV RDIMM/LV 1066 1333 1600, Load Reduced 1333 1333LV
# of Memory Channels	8
Max Memory Bandwidth	102.4 GB/s
Physical Address Extensions	46-bit
# of DIMMs	16
ECC Memory Supported ‡	Yes

Graphics Specifications	
Integrated Graphics ‡	Yes
Graphics Output	15-pin VGA
Intel® Clear Video Technology	No
Discrete Graphics	Supported

Expansion Options	
PCI Express Revision	3
Max # of PCI Express Lanes	84
PCIe x4 Gen 3	0
PCIe x8 Gen 3	1
PCIe x16 Gen 3	4
PCIe x1 Gen 2.x	0
PCIe x4 Gen 2.x	1
PCIe x8 Gen 2.x	0
PCIe x16 Gen 2.x	0

I/O Specifications	
USB Revision	USB 2.0
# of USB Ports	5
USB 2.0 Configuration (Back + Internal)	4

Add to Compare

RELATED PRODUCTS

- Dual-Socket Server Boards
- Intel® Server Board S2600CO Family
- Products formerly Copper Pass
- Intel® C602 Chipset

- Visit the Embedded Design Center >

QUICK LINKS

- No Datasheet Available
- Export Full Specifications
- Additional Information
- Search Distributors
- Software Downloads
- Support Overview
- Search all of intel.com

PCN/MDDS Information

916033: PCN | MDDS

Total # of SATA Ports	10
RAID Configuration	Up to SW Raid 5 (LSI + RSTE)
# of Serial Ports	2
# of LAN Ports	4
Integrated LAN	4x 1GbE
Embedded USB (eUSB) Solid State Drive Option	Yes
Integrated SAS Ports	4
Integrated InfiniBand*	No

Package Specifications

Max CPU Configuration	2
Low Halogen Options Available	See MDDS

Advanced Technologies

Intel® Virtualization Technology for Directed I/O (VT-d) ‡	Yes
Intel® vPro Technology ‡	No
Intel® ME Firmware Version	No
Intel® Remote Wake Technology	No
Intel® Remote PC Assist Technology	No
Intel® Remote Management Module Support	Yes
Intel® Node Manager	Yes
Intel® CIRA Technology	No
TPM	Yes
TPM Version	1.2
Intel® Quick Resume Technology	No
Intel® Quiet System Technology	No
Intel® HD Audio Technology	No
Intel® AC97 Technology	No
Intel® Matrix Storage Technology	Yes
Intel® Fast Memory Access	Yes
Intel® Flex Memory Access	Yes
Intel® I/O Acceleration Technology	True
Intel® Advanced Management Technology	Yes
Intel® Server Customization Technology	Yes
Intel® Build Assurance Technology	Yes
Intel® Efficient Power Technology	Yes
Intel® Quiet Thermal Technology	Yes

Intel® Data Protection Technology

AES New Instructions	Yes

Intel® Platform Protection Technology

Trusted Execution Technology ‡	Yes
Anti-Theft Technology	No

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"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.
Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.
‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.
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System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.
Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

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